

WEST Search History

DATE: Friday, September 29, 2006

| Hide? | Set Name | Query | Hit Count |
|--------------------------|----------|---|-----------|
| | | <i>DB=PGPB,USPT; PLUR=YES; OP=ADJ</i> | |
| <input type="checkbox"/> | L19 | ((HF dip) same (RCA clean) same (NF3 clean) same (hydrogen bake) same (polysilicon deposition)) | 0 |
| <input type="checkbox"/> | L18 | ((HF dip) same (RCA clean) same (NF3 clean) same (hydrogen bake) same (polysilicon deposition)) AND @pd>20060927 | 0 |
| <input type="checkbox"/> | L17 | ((decontaminat\$ or remov\$) and ((hydrogen-adsorbed layer) or (hydrogen termination)) and forming and (nitrogen fluoride)) | 5 |
| <input type="checkbox"/> | L16 | ((integrated circuit) or semiconductor) with (removing or cleaning) with forming with hydrogen termination | 0 |
| <input type="checkbox"/> | L15 | ((integrated circuit) or semiconductor) with (removing or cleaning) with forming with hydrogen termination AND @pd>20060927 | 0 |
| <input type="checkbox"/> | L14 | ((integrated circuit) or semiconductor with removing or cleaning) with (forming with hydrogen termination)) AND @pd>20060927 | 0 |
| <input type="checkbox"/> | L13 | ((integrated circuit) or semiconductor) with (removing or cleaning)) AND @pd>20060927 AND @pd>20060929 | 0 |
| <input type="checkbox"/> | L12 | ((HF dip) and (RCA clean) and (NF3 clean) and (hydrogen bake) and (polysilicon deposition)) | 1 |
| <input type="checkbox"/> | L11 | ((integrated circuit) or (semiconductor)) with (removing or cleaning) | 42424 |
| <input type="checkbox"/> | L10 | ((integrated circuit) or semiconductor) with (removing or cleaning)) AND @pd>20060927 AND @pd>20060929 | 0 |
| <input type="checkbox"/> | L9 | ((exposing with (nitrogen containing gas) or (nitrogen fluoride) with (integrated circuit) or semiconductor) same (forming with hydrogen termination)) | 17 |
| <input type="checkbox"/> | L8 | ((HF dip) and (RCA clean) and (NF3 clean) and (hydrogen bake) and (polysilicon deposition)) | 1 |
| <input type="checkbox"/> | L7 | ((HF dip) and (RCA clean) and (NF3 clean) and (hydrogen bake) and (polysilicon deposition)) AND @pd>20060927 | 0 |
| | | <i>DB=EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i> | |
| <input type="checkbox"/> | L6 | ((HF dip) and (RCA clean) and (NF3 clean) and (hydrogen bake) and (polysilicon deposition)) AND @pd>20060927 | 0 |
| | | <i>DB=PGPB,USPT; PLUR=YES; OP=ADJ</i> | |
| <input type="checkbox"/> | L5 | ((exposing with (nitrogen containing gas) or (nitrogen fluoride) with (integrated circuit) or semiconductor) same (forming with hydrogen termination)) AND @pd>20060927 | 0 |
| <input type="checkbox"/> | L4 | ((exposing) with ((nitrogen containing gas) or (nitrogen fluoride)) with ((integrated circuit) or semiconductor)) AND @pd>20060927 | 0 |
| <input type="checkbox"/> | L3 | ((integrated circuit) or semiconductor) with (removing or cleaning)) AND | 77 |

| | | | |
|--------------------------|----|--|----|
| <input type="checkbox"/> | L2 | @pd>20060927 (((integrated circuit) or semiconductor) with (removing or cleaning)) AND @pd>20060927 | 77 |
| <input type="checkbox"/> | L1 | ((exposing) with ((nitrogen containing gas) or (nitrogen fluoride)) with ((integrated circuit) or semiconductor)) AND @pd>20060927 | 0 |

END OF SEARCH HISTORY